

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	548	thixotropic adj index	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/04 15:25
S2	37	thixotropic adj index with epoxy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 16:55
S3	37	thixotropic adj index with epoxy and (viscosity or thixotropic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 16:56
S4	37	thixotropic adj index with epoxy and (viscosity or thixotropic or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 16:57
S5	4	"690013".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 16:56
S6	224	thixotropic adj index and epoxy and (viscosity or thixotropic or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 16:57
S7	0	S4 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 16:57
S8	1	S6 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 17:05

S9	31090	alps adj electric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 17:05
S10	226	alps adj electric and silicone	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 17:06
S11	11	alps adj electric and thixotropic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 18:27
S12	6	(JP-08236652-\$ or JP-08213498-\$ or JP-11233537-\$).did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 18:30
S13	282	(encapsulant encapsulation encapsulating) SAME (modulus near (elasticity young youngs) coefficient near elastic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 18:53
S14	10	S13 and thixotropic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 18:35
S15	237	(encapsulant encapsulation encapsulating) and (modulus near (elasticity young youngs) coefficient near elastic) SAME MPA	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 19:12
S16	2	JP-2001332661-\$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 19:36

S17	148	S15 and @pd>"20020627"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/05 19:36
S18	540	(257/659).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/03/06 14:18
S19	45	S18 and (solder soldered soldering) same shield	US-PGPUB; USPAT	OR	OFF	2005/03/06 14:19
S20	7525	(257/659,666,669,701,704,746, 779,782,783,787,788,791).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/03/06 14:19
S21	1	(257/791).CCLS. and (solder soldered soldering) same shield	US-PGPUB; USPAT	OR	OFF	2005/03/06 14:36
S22	110	(257/791).CCLS. and (chip die)	US-PGPUB; USPAT	OR	OFF	2005/03/06 14:20
S23	69	(257/791).CCLS. and (chip die) and silicone	US-PGPUB; USPAT	OR	OFF	2005/03/06 14:20
S24	56	(257/791).CCLS. and (solder soldered soldering) and silicone	US-PGPUB; USPAT	OR	OFF	2005/03/06 15:18
S25	1	("20020031672").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/03/06 15:18
S26	1	S25 and (solder soldered soldering) and silicone and thixotropic	US-PGPUB; USPAT	OR	OFF	2005/03/06 15:18